

Trisil™ for telecom equipment protection

Features

- Bidirectional crowbar protection
- Voltage range from 62 V to 320 V
- Low capacitance from 12 pF to 20 pF @ 50 V
- Low leakage current : $I_R = 2 \mu\text{A max}$
- Holding current: $I_H = 150 \text{ mA min}$
- Repetitive peak pulse current :
 $I_{PP} = 50 \text{ A (10/1000 } \mu\text{s)}$

Main applications

Telecommunication equipment such as:

- Analog and digital line cards (xDSL, T1/E1, ISDN, ...)
- Terminals (phone, fax, modem, ...) and central office equipment

Description

These Trisil series have been designed to protect telecommunication equipment against lightning and transient induced by AC power lines.

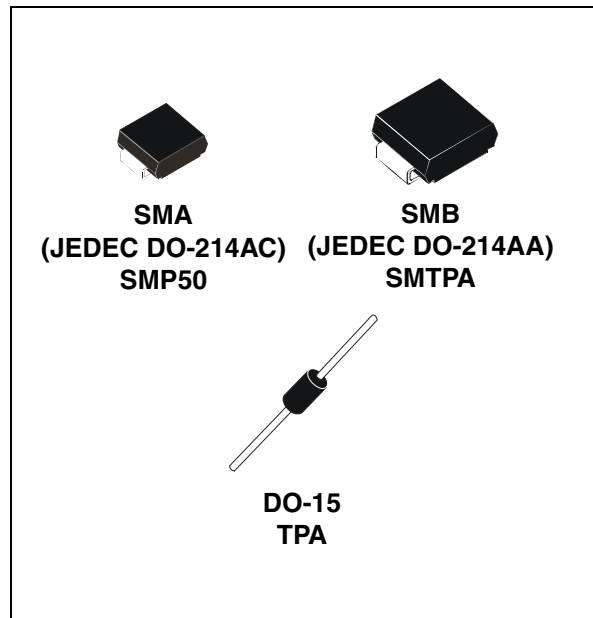
They are available in SMA, SMB and DO-15 packages.

Benefits

Trisils are not subject to ageing and provide a fail safe mode in short circuit for a better protection. They are used to help equipment to meet various standards such as UL1950, IEC950 / CSA C22.2, UL1459 and FCC part 68.

Trisils have UL94 V0 approved resin. SMA and SMB packages are JEDEC registered (DO-214AC and DO-214AA).

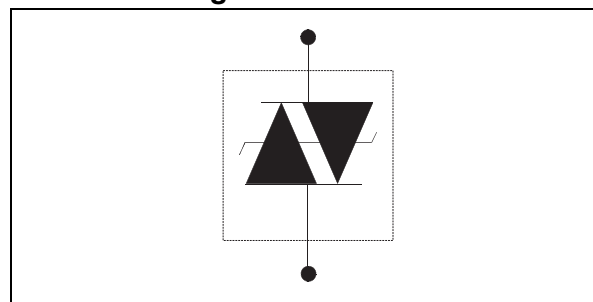
Trisils are UL497B approved (file: E136224).



Order codes

| Part Number | Marking |
|-------------|--|
| SMP50-xxx | See Ordering Information on page 9 |
| TPAxxx | |
| SMTPAxxx | |

Schematic Diagram



TM: TRISIL is a trademark of STMicroelectronics

1 Characteristics

Table 1. Compliant with the following standards

| Standard | Peak Surge Voltage (V) | Waveform Voltage | Required peak current (A) | Current waveform | Minimum serial resistor to meet standard (Ω) |
|-------------------------------------|------------------------|------------------|---------------------------|------------------|--|
| GR-1089 Core First level | 2500 | 2/10 μs | 500 | 2/10 μs | 20 |
| | 1000 | 10/1000 μs | 100 | 10/1000 μs | 10 |
| GR-1089 Core Second level | 5000 | 2/10 μs | 500 | 2/10 μs | 40 |
| GR-1089 Core Intra-building | 1500 | 2/10 μs | 100 | 2/10 μs | 0 |
| ITU-T-K20/K21 | 6000 | 10/700 μs | 150 | 5/310 μs | 53 |
| | 1500 | | 37.5 | | 0 |
| ITU-T-K20 (IEC61000-4-2) | 8000 | 1/60 ns | ESD contact discharge | | 0 |
| | 15000 | | ESD air discharge | | 0 |
| VDE0433 | 4000 | 10/700 μs | 100 | 5/310 μs | 21.5 |
| | 2000 | | 50 | | 0 |
| VDE0878 | 4000 | 1.2/50 μs | 100 | 1/20 μs | 0 |
| | 2000 | | 50 | | 0 |
| IEC61000-4-5 | 4000 | 10/700 μs | 100 | 5/310 μs | 21.5 |
| | 4000 | 1.2/50 μs | 100 | 8/20 μs | 0 |
| FCC Part 68, lightning surge type A | 1500 | 10/160 μs | 200 | 10/160 μs | 12.5 |
| | 800 | 10/560 μs | 100 | 10/560 μs | 6.5 |
| FCC Part 68, lightning surge type B | 1000 | 9/720 μs | 25 | 5/320 μs | 0 |

Table 2. Absolute ratings (T_{amb} = 25° C)

| Symbol | Parameter | Value | Unit |
|------------------|---|-------------|------|
| I _{PP} | Repetitive peak pulse current (see Figure 1) | 10/1000 μs | 50 |
| | | 8/20 μs | 150 |
| | | 10/560 μs | 55 |
| | | 5/310 μs | 65 |
| | | 10/160 μs | 75 |
| | | 1/20 μs | 100 |
| I _{FS} | Fail-safe mode : maximum current ⁽¹⁾ | 8/20 μs | 2.5 |
| | | | kA |
| I _{TSM} | Non repetitive surge peak on-state current (sinusoidal) | t = 0.2 s | 16 |
| | | t = 1 s | 11.5 |
| | | t = 2 s | 10 |
| | | t = 15 mn | 3.5 |
| I ² t | I ² t value for fusing | t = 16.6 ms | 6.2 |
| | | t = 20 ms | 6.5 |
| T _{stg} | Storage temperature range | -55 to 150 | °C |
| T _j | Maximum junction temperature | 150 | °C |
| T _L | Maximum lead temperature for soldering during 10 s. | 260 | °C |

1. in fail safe mode, the device acts as a short circuit

Table 3. Thermal resistances

| Symbol | Parameter | Value | | | Unit |
|---------------|---|-------|-----|-----|---------------|
| | | DO-15 | SMA | SMB | |
| $R_{th(j-a)}$ | Junction to ambient (with recommended footprint or with $L_{lead} = 10$ mm for DO-15) | 100 | 120 | 100 | $^{\circ}C/W$ |
| $R_{th(j-l)}$ | Junction to leads ($L_{lead} = 10$ mm for DO-15) | 60 | 30 | 20 | $^{\circ}C/W$ |

Table 4. Electrical characteristics - definitions ($T_{amb} = 25^{\circ}C$)

| Symbol | Parameter |
|----------|----------------------------|
| V_{RM} | Stand-off voltage |
| V_{BR} | Breakdown voltage |
| V_{BO} | Breakover voltage |
| I_{RM} | Leakage current |
| I_{PP} | Peak pulse current |
| I_{BO} | Breakover current |
| I_H | Holding current |
| V_R | Continuous reverse voltage |
| I_R | Leakage current at V_R |
| C | Capacitance |



Table 5. Electrical characteristics - values ($T_{amb} = 25^{\circ}C$)

| Types | $I_{RM} @ V_{RM}$ | | $I_R @ V_R^{(1)}$ | | Dynamic $V_{BO}^{(2)}$ | Static $V_{BO} @ I_{BO}^{(3)}$ | | $I_H^{(4)}$ | $C^{(5)}$ | $C^{(6)}$ |
|--------------------------------|-------------------|-----|-------------------|-----|------------------------|--------------------------------|------|-------------|-----------|-----------|
| | max. | | max. | | max. | max. | max. | min. | typ. | typ. |
| | μA | V | μA | V | V | V | mA | mA | pF | pF |
| SMP50-62 / TPA62 SMTPA62 | | 56 | | 62 | 85 | 82 | | | 20 | 40 |
| SMP50-68 / TPA68 SMTPA68 | | 61 | | 68 | 93 | 90 | | | 20 | 40 |
| SMP50-100 / TPA100 SMTPA100 | | 90 | | 100 | 135 | 133 | | | 16 | 35 |
| SMP50-120 / TPA120 SMTPA120 | | 108 | | 120 | 160 | 160 | | | 16 | 30 |
| SMP50-130 / TPA130 SMTPA130 | | 117 | | 130 | 173 | 173 | | | 14 | 30 |
| SMP50-180 / TPA180 SMTPA180 | 2 | 162 | 5 | 180 | 235 | 240 | 800 | 150 | 14 | 25 |
| SMP50-200 / TPA200 SMTPA200 | | 180 | | 200 | 262 | 267 | | | 12 | 25 |
| SMP50-220 / TPA220 SMTPA220 | | 198 | | 220 | 285 | 293 | | | 12 | 25 |
| SMP50-240 / TPA240 SMTPA240 | | 216 | | 240 | 300 | 320 | | | 12 | 25 |
| SMP50-270 / TPA270 SMTPA270 | | 243 | | 270 | 350 | 360 | | | 12 | 25 |
| SMP50-320 / SMTPA320 | | 290 | | 320 | 400 | 400 | | | 12 | 25 |

1. I_R measured at V_R guarantee $V_{BR} \min \geq V_R$
2. See functional test circuit 1(Figure 9.)
3. See test circuit 2(Figure 10.)
4. See functional holding current test circuit 3(Figure 11.)
5. $V_R = 50 V$ bias, $V_{RMS} = 1 V$, $F = 1 MHz$
6. $V_R = 2 V$ bias, $V_{RMS} = 1 V$, $F = 1 MHz$

Figure 1. Pulse waveform (10/1000 μs)



Figure 2. Non repetitive surge peak on-state current versus overload duration



Figure 3. On-state voltage versus on-state current (typical values)



Figure 4. Relative variation of holding current versus junction temperature



Figure 5. Relative variation of breakover voltage versus junction temperature



Figure 6. Relative variation of leakage current versus reverse voltage applied (typical values)



Figure 7. Variation of thermal impedance junction to ambient versus pulse duration (Printed circuit board FR4, SCu = 35 μm, recommended pad layout)



Figure 8. Relative variation of junction capacitance versus reverse voltage applied (typical values)



Figure 9. Test circuit 1 for Dynamic I_{BO} and V_{BO} parameters



Figure 10. Test circuit 2 for I_{BO} and V_{BO} parameters



Figure 11. Test circuit 3 for dynamic I_H parameters



2 Ordering information scheme



3 Package information

- Epoxy meets UL94, V0

Table 6. SMA dimensions

| Ref. | Dimensions | | | |
|------|-------------|------|--------|-------|
| | Millimeters | | Inches | |
| | Min. | Max. | Min. | Max. |
| A1 | 1.90 | 2.45 | 0.075 | 0.094 |
| A2 | 0.05 | 0.20 | 0.002 | 0.008 |
| b | 1.25 | 1.65 | 0.049 | 0.065 |
| c | 0.15 | 0.40 | 0.006 | 0.016 |
| D | 2.25 | 2.90 | 0.089 | 0.114 |
| E | 4.80 | 5.35 | 0.189 | 0.211 |
| E1 | 3.95 | 4.60 | 0.156 | 0.181 |
| L | 0.75 | 1.50 | 0.030 | 0.059 |

Figure 12. Footprint, dimensions in mm (inches)



Table 7. SMB dimensions

| Ref. | Dimensions | | | |
|------|-------------|------|--------|-------|
| | Millimeters | | Inches | |
| | Min. | Max. | Min. | Max. |
| A1 | 1.90 | 2.45 | 0.075 | 0.096 |
| A2 | 0.05 | 0.20 | 0.002 | 0.008 |
| b | 1.95 | 2.20 | 0.077 | 0.087 |
| c | 0.15 | 0.40 | 0.006 | 0.016 |
| E | 5.10 | 5.60 | 0.201 | 0.220 |
| E1 | 4.05 | 4.60 | 0.159 | 0.181 |
| D | 3.30 | 3.95 | 0.130 | 0.156 |
| L | 0.75 | 1.50 | 0.030 | 0.059 |

Figure 13. Footprint, dimensions in mm (inches)

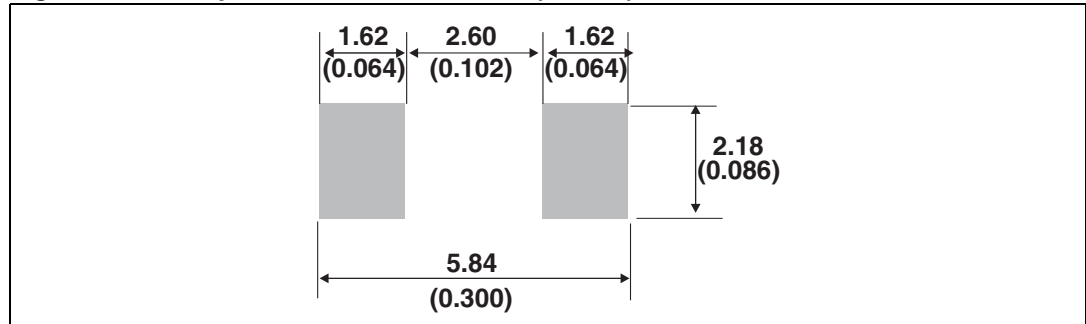


Table 8. DO-15 dimensions

| Ref. | Dimensions | | | |
|------|-------------|------|--------|-------|
| | Millimeters | | Inches | |
| | Min. | Max. | Min. | Max. |
| A | 6.05 | 6.75 | 0.238 | 0.266 |
| B | 2.95 | 3.53 | 0.116 | 0.139 |
| C | 26 | 31 | 1.024 | 1.220 |
| D | 0.71 | 0.88 | 0.028 | 0.035 |

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com.

4 Ordering Information

| Part Number | Marking | Package | Weight | Base qty | Delivery mode |
|-------------|---------|---------|---------|----------|---------------|
| SMP50-62 | V06 | SMA | 0.068 g | 5000 | Tape & reel |
| SMP50-68 | V07 | | | | |
| SMP50-100 | V10 | | | | |
| SMP50-120 | V12 | | | | |
| SMP50-130 | V13 | | | | |
| SMP50-180 | V18 | | | | |
| SMP50-200 | V20 | | | | |
| SMP50-220 | V22 | | | | |
| SMP50-240 | V24 | | | | |
| SMP50-270 | V27 | | | | |
| SMP50-320 | V32 | | | | |
| SMTPA62 | U01 | | | | |
| SMTPA68 | U05 | | | | |
| SMTPA100 | U13 | | | | |
| SMTPA120 | U17 | | | | |
| SMTPA130 | U19 | | | | |
| SMTPA180 | U25 | | | | |
| SMTPA200 | U27 | | | | |
| SMTPA220 | U31 | | | | |
| SMTPA240 | U35 | | | | |
| SMTPA270 | U39 | | | | |
| SMTPA320 | U47 | | | | |
| TPA62 | TPA62 | DO-15 | 0.40 g | 1000 | Ammopack |
| TPA62RL | | | | 6000 | Tape & reel |
| TPA68 | TPA68 | | | 1000 | Ammopack |
| TPA68RL | | | | 6000 | Tape & reel |
| TPA100 | TPA100 | | | 1000 | Ammopack |
| TPA100RL | | | | 6000 | Tape & reel |
| TPA120 | TPA120 | | | 1000 | Ammopack |
| TPA130 | TPA130 | | | 1000 | Ammopack |
| TPA130RL | | | | 6000 | Tape & reel |
| TPA180 | TPA180 | | | 1000 | Ammopack |
| TPA180RL | | | | 6000 | Tape & reel |
| TPA200 | TPA200 | | | 1000 | Ammopack |
| TPA200RL | | | | 6000 | Tape & reel |
| TPA220 | TPA220 | | | 1000 | Ammopack |
| TPA220RL | | | | 6000 | Tape & reel |
| TPA240 | TPA240 | | | 1000 | Ammopack |
| TPA240RL | | | | 6000 | Tape & reel |
| TPA270 | TPA270 | | | 1000 | Ammopack |
| TPA270RL | | | | 6000 | Tape & reel |

5 Revision History

| Date | Revision | Description of Changes |
|-------------|----------|--|
| 16-Nov-2004 | 1 | SMP50, SMTPA and TPA datasheets merge. |
| 30-Mar-2007 | 2 | Reformatted to current standards. Updated I_{PP} value in Table 2 . Added part numbers SMP50-320 and SMTPA320. Updated dimensions and footprint for SMA and footprint for SMB. |
| 12-Jun-2007 | 3 | Corrected typographical error in part number. Added dimensions in inches to footprint illustrations. |

Please Read Carefully:

Information in this document is provided solely in connection with ST products. STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, modifications or improvements, to this document, and the products and services described herein at any time, without notice.

All ST products are sold pursuant to ST's terms and conditions of sale.

Purchasers are solely responsible for the choice, selection and use of the ST products and services described herein, and ST assumes no liability whatsoever relating to the choice, selection or use of the ST products and services described herein.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted under this document. If any part of this document refers to any third party products or services it shall not be deemed a license grant by ST for the use of such third party products or services, or any intellectual property contained therein or considered as a warranty covering the use in any manner whatsoever of such third party products or services or any intellectual property contained therein.

UNLESS OTHERWISE SET FORTH IN ST'S TERMS AND CONDITIONS OF SALE ST DISCLAIMS ANY EXPRESS OR IMPLIED WARRANTY WITH RESPECT TO THE USE AND/OR SALE OF ST PRODUCTS INCLUDING WITHOUT LIMITATION IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION), OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT.

UNLESS EXPRESSLY APPROVED IN WRITING BY AN AUTHORIZED ST REPRESENTATIVE, ST PRODUCTS ARE NOT RECOMMENDED, AUTHORIZED OR WARRANTED FOR USE IN MILITARY, AIR CRAFT, SPACE, LIFE SAVING, OR LIFE SUSTAINING APPLICATIONS, NOR IN PRODUCTS OR SYSTEMS WHERE FAILURE OR MALFUNCTION MAY RESULT IN PERSONAL INJURY, DEATH, OR SEVERE PROPERTY OR ENVIRONMENTAL DAMAGE. ST PRODUCTS WHICH ARE NOT SPECIFIED AS "AUTOMOTIVE GRADE" MAY ONLY BE USED IN AUTOMOTIVE APPLICATIONS AT USER'S OWN RISK.

Resale of ST products with provisions different from the statements and/or technical features set forth in this document shall immediately void any warranty granted by ST for the ST product or service described herein and shall not create or extend in any manner whatsoever, any liability of ST.

ST and the ST logo are trademarks or registered trademarks of ST in various countries.

Information in this document supersedes and replaces all information previously supplied.

The ST logo is a registered trademark of STMicroelectronics. All other names are the property of their respective owners.

© 2007 STMicroelectronics - All rights reserved

STMicroelectronics group of companies

Australia - Belgium - Brazil - Canada - China - Czech Republic - Finland - France - Germany - Hong Kong - India - Israel - Italy - Japan - Malaysia - Malta - Morocco - Singapore - Spain - Sweden - Switzerland - United Kingdom - United States of America

www.st.com

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

Skype отдела продаж:

moschip.ru

moschip.ru_4

moschip.ru_6

moschip.ru_9